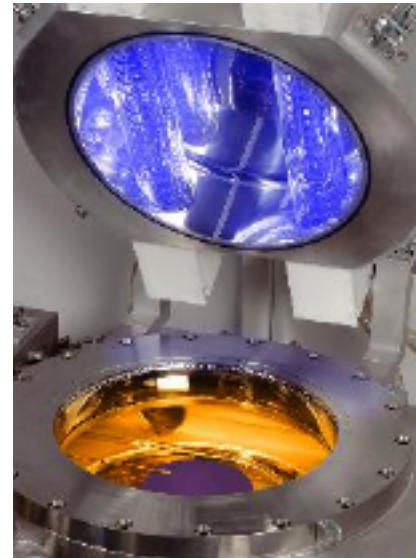


JetClip sg

Low Temperature Rapid Thermal Annealing

Densification and crystallization for sol-gel, MOD, CSD and MOCVD layers

The Jipelec JetClip sg Low Temperature Rapid Thermal Annealing (RTA) system utilizes a high power ultraviolet source to assist densification and crystallization of layers obtained by sol-gel, MOD, CSD and MOCVD processes. When used for ferroelectric and high-k materials such as PZT, SBT and BST, post annealing temperature can be reduced, a requirement in new generation devices.



The Jipelec JetClip sg is a SEMI-MESC compatible Low Temperature Rapid Thermal Processing cluster module for wafer sizes up to 200 mm diameter.

Jipelec PIMS PC control allows for full process monitoring, data acquisition and pyrometer calibration for a large range of substrates.

A robot handling unit and loadlock are available upon request. Stand alone systems can also be supplied.

Furnace: Unique lamp design to provide process repeatability with thermal stability
Accurate temperature measurement and control using a pyrometer
New thermally efficient reactor design



Applications: PZT: Sensors, MEMS
Glass: optical waveguides
SBT: FeRAM
BST: DRAM

Features: Up to 200 mm wafers
Cold wall chamber technology
Infrared halogen lamp furnace
222 nm Excimer lamps
Pyrometer temperature control
Atmospheric & vacuum process capability
One purge gas line
Up to 6 gas lines with MFC

Performance: Temperature range: ambient to 1000°C
Ramp rate: 1°C/s to 200°C/s
Pyrometer control: 150°C to 1000°C